

In re Application of:
Landau, et al.

Serial No.: 10/622,001

Confirmation No.: 2266

Filed: July 17, 2003

For: Electro-Chemical
Deposition System and
Method of Electroplating on
Substrates

Group Art Unit: 1746

Examiner: Bruce F. Bell

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING OR TRANSMISSION

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, or electronically transmitted to the U.S. Patent and Trademark Office via EFS-Web to the attention of Examiner Bruce F. Bell, on the date shown below.

January 19, 2007
Date

Steven H. VerSteege

Dear Sir:

RESPONSE TO OFFICE ACTION DATED OCTOBER 19, 2006

In response to the Office Action dated October 19, 2006, having a shortened statutory period for response set to expire on January 19, 2007, please enter this response and reconsider the claims pending in the application for the reasons discussed below. Although Applicant believes that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/002601.R02/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

Amendments to the Specification begin on page 2 of this paper. **Amendments to the Claims** are reflected in the listing of claims which begins on page 5 of this paper. **Remarks** begin on page 19 of this paper.